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SPA08N80C3

CoolMOS™ Power Transistor

Features

- New revolutionary high voltage technology
- Extreme dv/dt rated
- High peak current capability
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant
- Ultra low gate charge
- Ultra low effective capacitances
- Fully isolated package (2500 VAC; 1 minute)

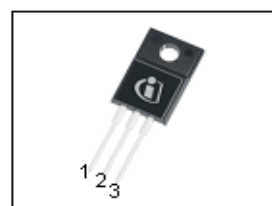
CoolMOS™ 800V designed for:

- Industrial application with high DC bulk voltage
- Switching Application (i.e. active clamp forward)

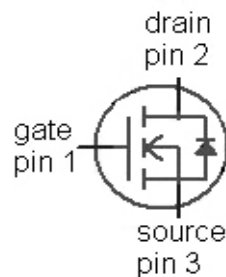
Product Summary

V_{DS}	800	V
$R_{DS(on)max} @ T_j = 25^{\circ}C$	0.65	Ω
$Q_{g,typ}$	45	nC

PG-TO220FP



Type	Package	Marking
SPA08N80C3	PG-TO220FP	08N80C3



Maximum ratings, at $T_j=25^{\circ}C$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current ²⁾	I_D	$T_C=25^{\circ}C$	8	A
		$T_C=100^{\circ}C$	5.1	
Pulsed drain current ³⁾	$I_{D,pulse}$	$T_C=25^{\circ}C$	24	
Avalanche energy, single pulse	E_{AS}	$I_D=1.6 A, V_{DD}=50 V$	340	mJ
Avalanche energy, repetitive $t_{AR}^{3),4)}$	E_{AR}	$I_D=8 A, V_{DD}=50 V$	0.2	
Avalanche current, repetitive $t_{AR}^{3),4)}$	I_{AR}		8	A
MOSFET dv/dt ruggedness	dv/dt	$V_{DS}=0 \dots 640 V$	50	V/ns
Gate source voltage	V_{GS}	static	± 20	V
		AC ($f > 1 Hz$)	± 30	
Power dissipation	P_{tot}	$T_C=25^{\circ}C$	40	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	$^{\circ}C$
Mounting torque		M2.5 screws	50	Ncm



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Maximum ratings, at $T_j=25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous diode forward current	I_S	$T_C=25\text{ }^{\circ}\text{C}$	8	A
Diode pulse current ⁽²⁾	$I_{S,pulse}$		24	
Reverse diode dv/dt ⁽⁴⁾	dv/dt		4	V/ns

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - case	R_{thJC}		-	-	3.8	K/W
Thermal resistance, junction - ambient	R_{thJA}	lead	-	-	80	
Soldering temperature, wave soldering only allowed at leads	T_{solder}	1.6 mm (0.063 in.) from case for 10s	-	-	260	$^{\circ}\text{C}$

Electrical characteristics, at $T_j=25\text{ }^{\circ}\text{C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$	800	-	-	V
Avalanche breakdown voltage	$V_{(BR)DS}$	$V_{GS}=0\text{ V}, I_D=8\text{ A}$	-	870	-	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=0.47\text{ mA}$	2.1	3	3.9	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=800\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^{\circ}\text{C}$	-	-	20	μA
		$V_{DS}=800\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ }^{\circ}\text{C}$	-	100	-	
Gate-source leakage current	I_{GSS}	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=5.1\text{ A}, T_j=25\text{ }^{\circ}\text{C}$	-	0.56	0.65	Ω
		$V_{GS}=10\text{ V}, I_D=5.1\text{ A}, T_j=150\text{ }^{\circ}\text{C}$	-	1.5	-	
Gate resistance	R_G	$f=1\text{ MHz}$, open drain	-	1.2	-	Ω



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Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=100\text{ V},$ $f=1\text{ MHz}$	-	1100	-	pF
Output capacitance	C_{oss}		-	46	-	
Effective output capacitance, energy related ⁵⁾	$C_{o(er)}$	$V_{GS}=0\text{ V}, V_{DS}=0\text{ V}$ to 480 V	-	36	-	
Effective output capacitance, time related ⁶⁾	$C_{o(tr)}$		-	99	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=400\text{ V},$ $V_{GS}=0/10\text{ V}, I_D=8\text{ A},$ $R_{GS}=10\ \Omega, T_J=25\text{ °C}$	-	25	-	ns
Rise time	t_r		-	15	-	
Turn-off delay time	$t_{d(off)}$		-	72	-	
Fall time	t_f		-	10	-	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DD}=640\text{ V}, I_D=8\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	6	-	nC
Gate to drain charge	Q_{gd}		-	22	-	
Gate charge total	Q_g		-	45	60	
Gate plateau voltage	$V_{plateau}$		-	5.5	-	V

Reverse Diode

Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=I_S=8\text{ A},$ $T_J=25\text{ °C}$	-	1	1.2	V
Reverse recovery time	t_{rr}	$V_R=400\text{ V}, I_F=I_S=8\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	550	-	ns
Reverse recovery charge	Q_{rr}		-	7	-	μC
Peak reverse recovery current	I_{rrm}		-	24	-	A

¹⁾ J-STD20 and JESD22

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Repetitive avalanche causes additional power losses that can be calculated as $P_{AV}=E_{AR} \cdot f$.

⁴⁾ $I_{SD} \leq I_D$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DClk} = 400\text{ V}$, $V_{peak} < V_{(BR)DSS}$, $T_J < T_{j,max}$, identical low side and high side switch

⁵⁾ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

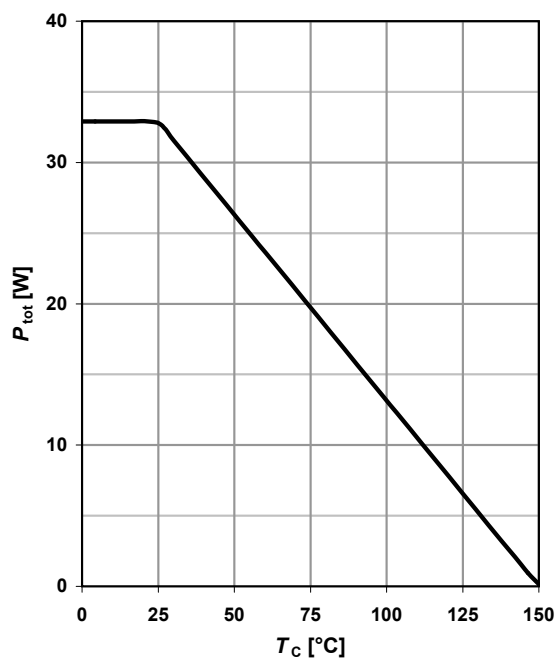
⁶⁾ $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .



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1 Power dissipation

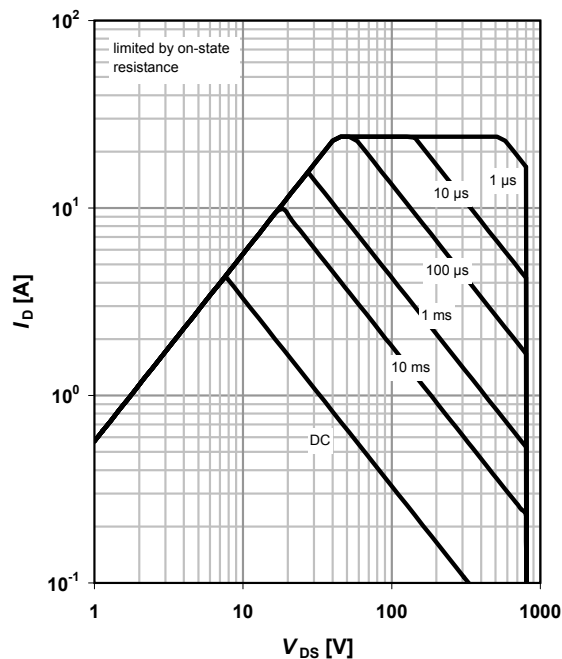
$$P_{\text{tot}} = f(T_C)$$



2 Safe operating area

$$I_D = f(V_{DS}); T_C = 25^\circ\text{C}; D = 0$$

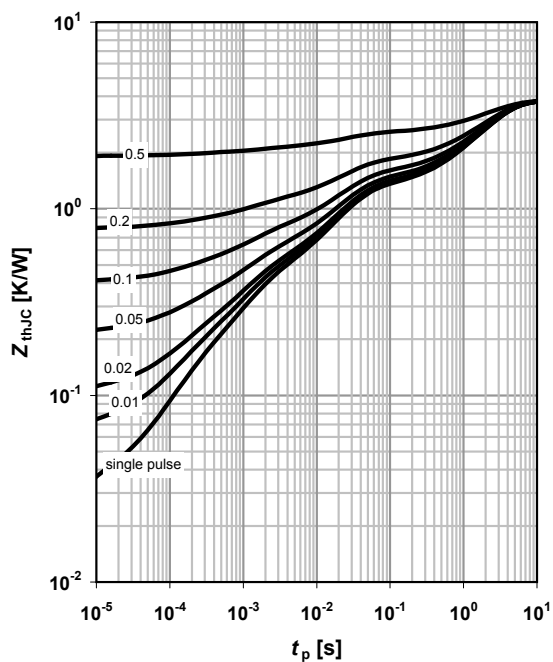
parameter: t_p



3 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

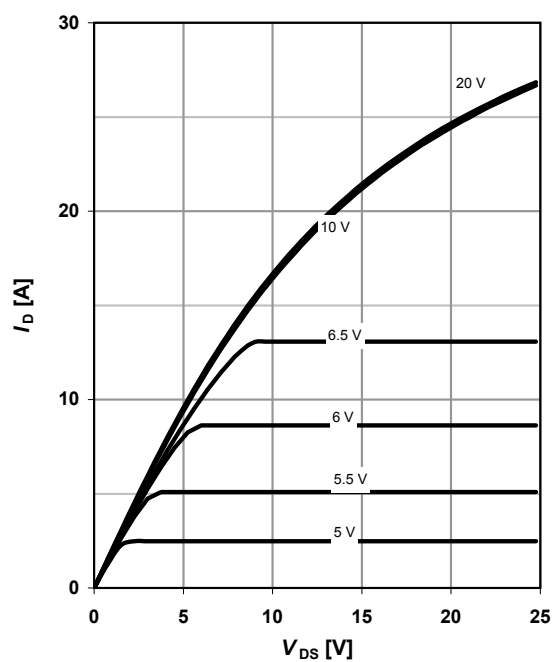
parameter: $D = t_p / T$



4 Typ. output characteristics

$$I_D = f(V_{DS}); T_J = 25^\circ\text{C}; t_p = 10 \mu\text{s}$$

parameter: V_{GS}



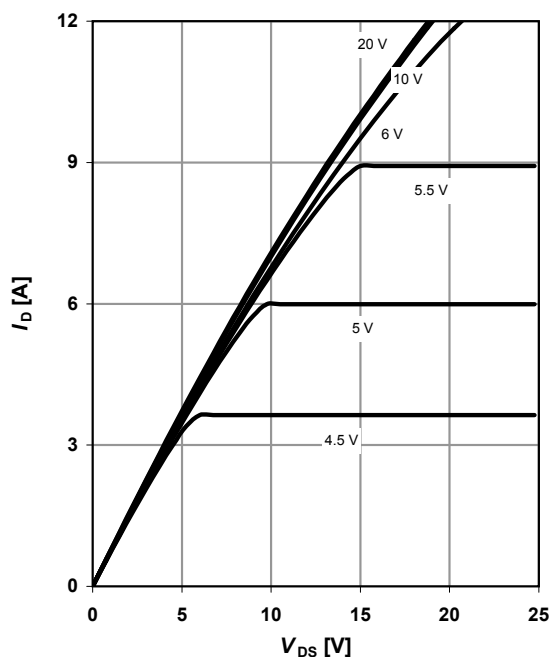


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5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 150^\circ\text{C}$; $t_p = 10\ \mu\text{s}$

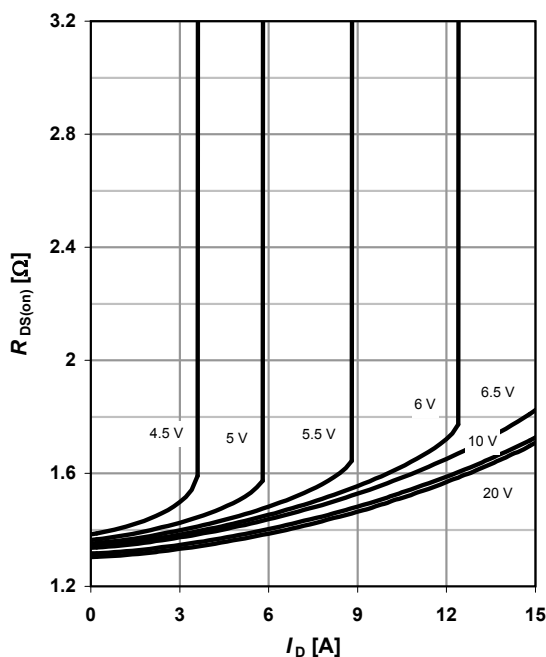
parameter: V_{GS}



6 Typ. drain-source on-state resistance

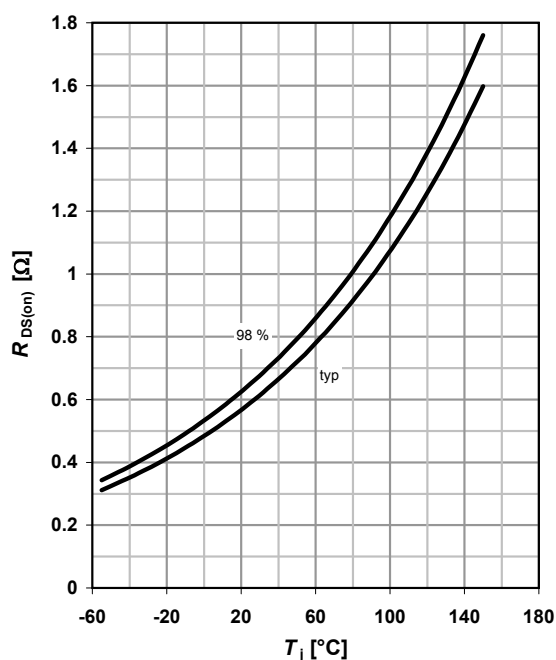
$R_{DS(on)} = f(I_D)$; $T_j = 150^\circ\text{C}$

parameter: V_{GS}



7 Drain-source on-state resistance

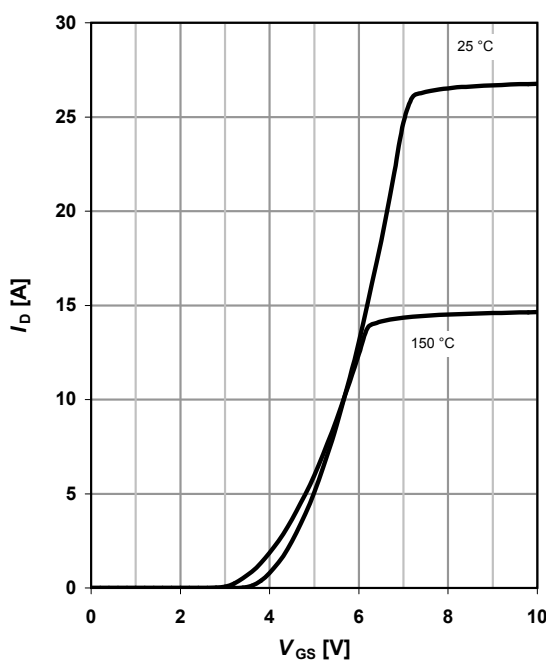
$R_{DS(on)} = f(T_j)$; $I_D = 5.1\text{ A}$; $V_{GS} = 10\text{ V}$



8 Typ. transfer characteristics

$I_D = f(V_{GS})$; $|V_{DS}| > 2|I_D|R_{DS(on)max}$; $t_p = 10\ \mu\text{s}$

parameter: T_j



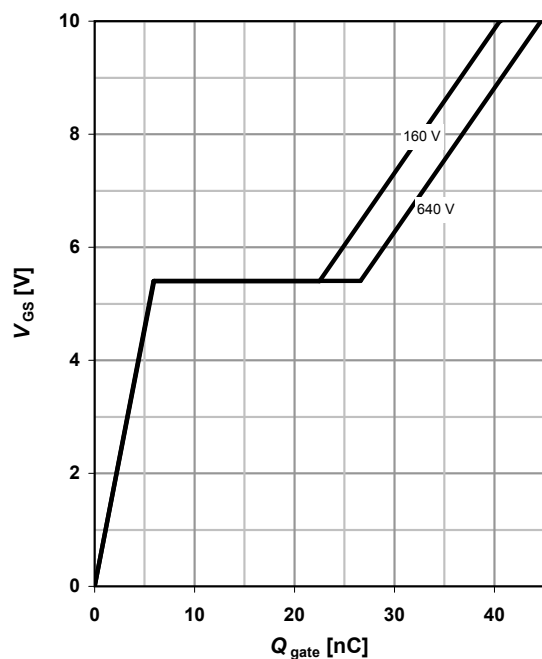


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9 Typ. gate charge

$V_{GS}=f(Q_{gate}); I_D=8\text{ A pulsed}$

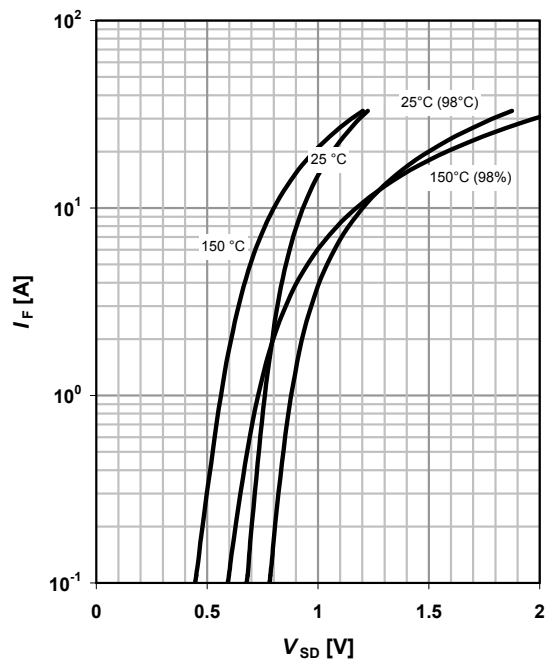
parameter: V_{DD}



10 Forward characteristics of reverse diode

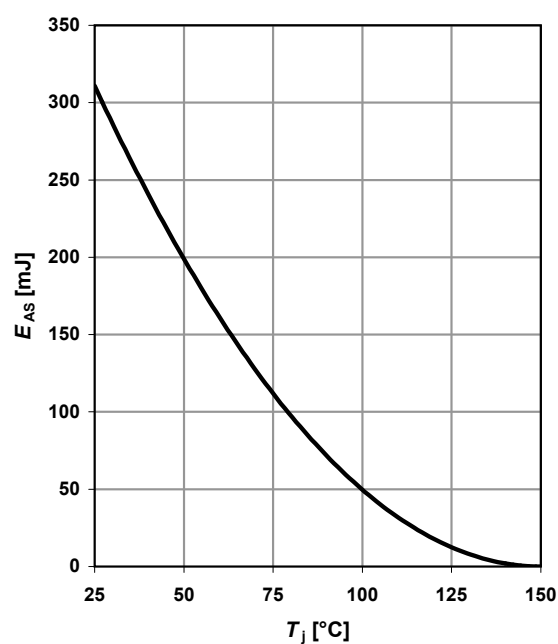
$I_F=f(V_{SD}); t_p=10\text{ }\mu\text{s}$

parameter: T_j



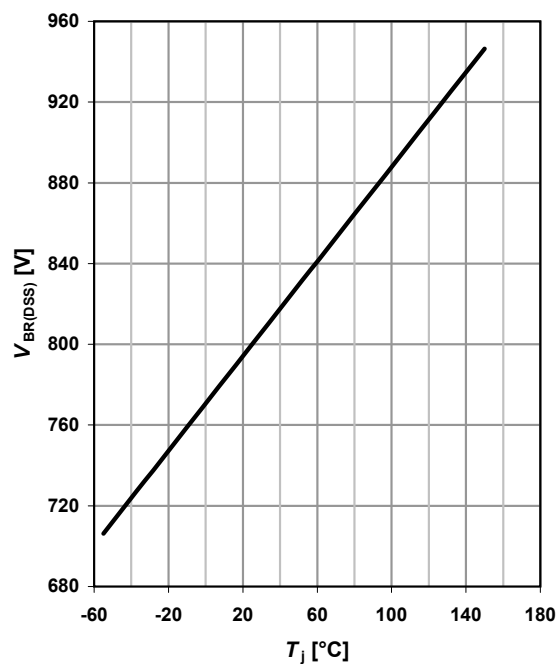
11 Avalanche energy

$E_{AS}=f(T_j); I_D=1.6\text{ A}; V_{DD}=50\text{ V}$



12 Drain-source breakdown voltage

$V_{BR(DSS)}=f(T_j); I_D=0.25\text{ mA}$

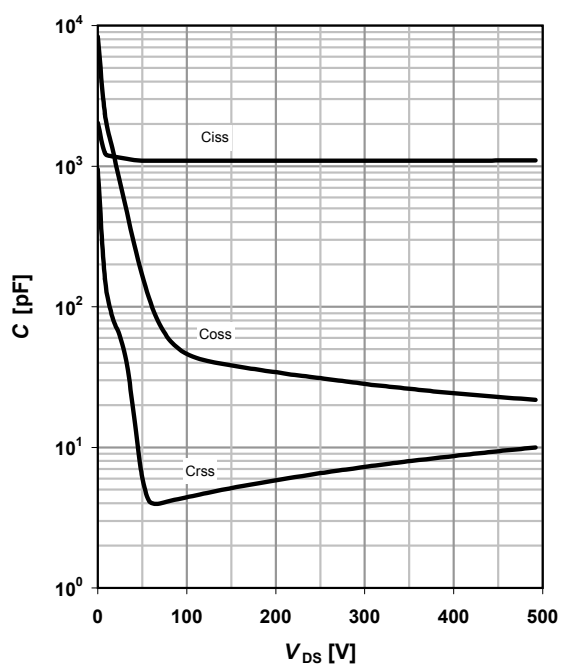




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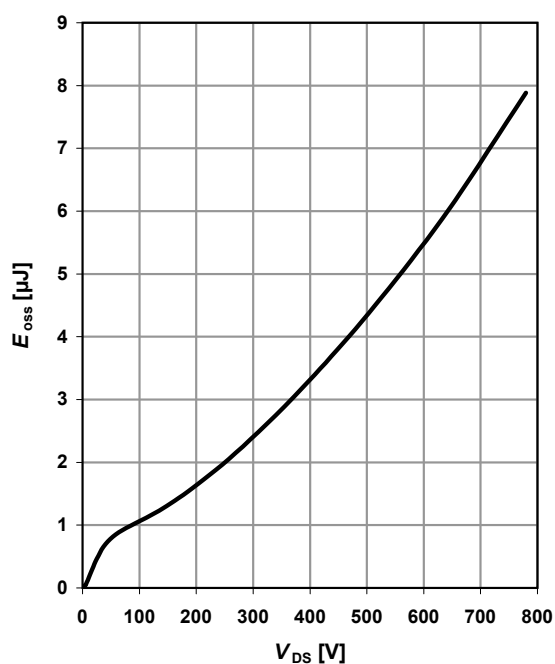
13 Typ. capacitances

$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



14 Typ. Coss stored energy

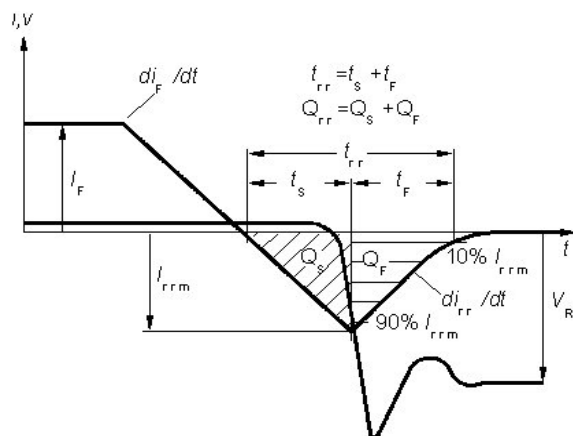
$E_{oss} = f(V_{DS})$





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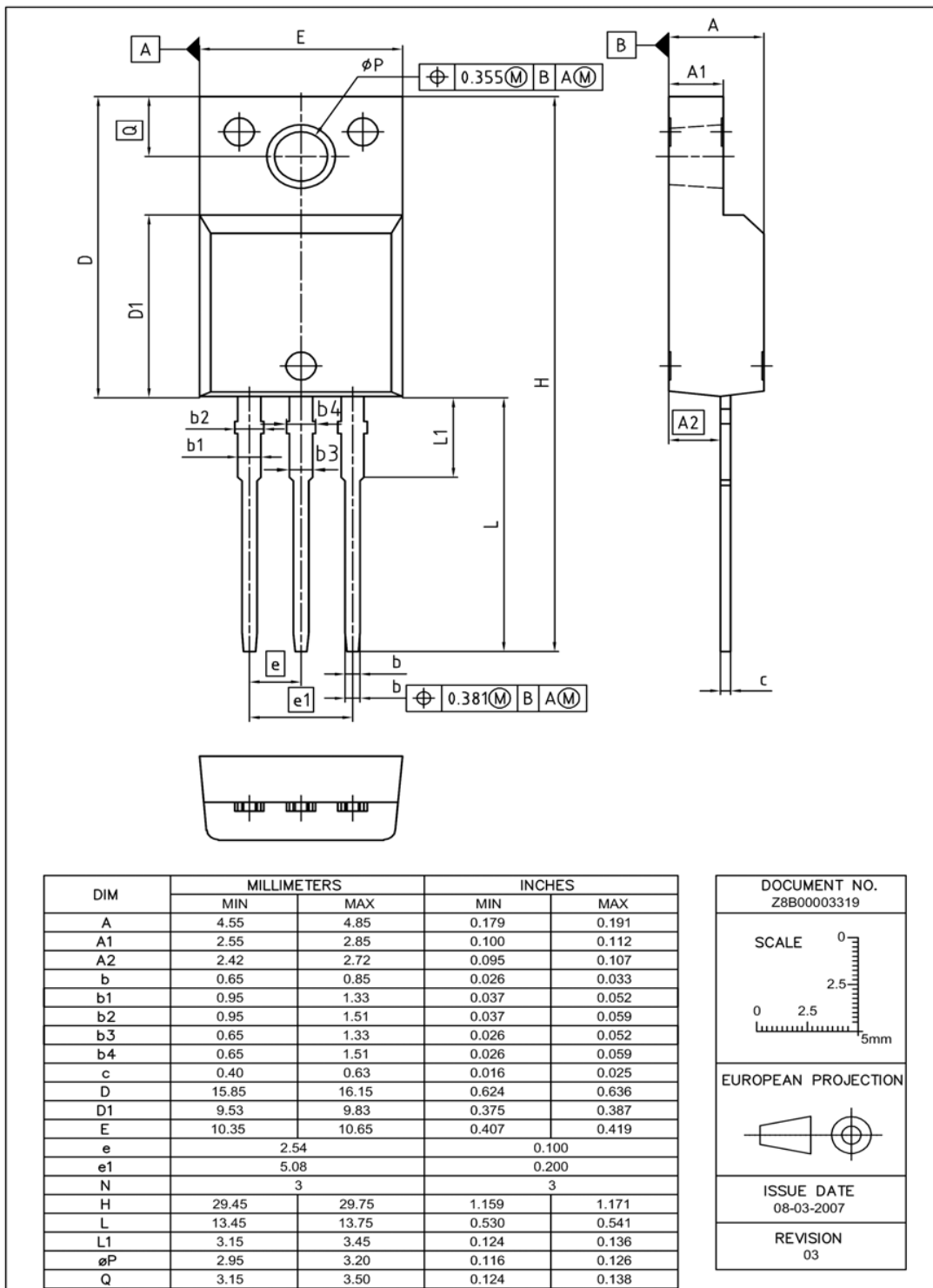
Definition of diode switching characteristics





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PG-TO220-3 (Fully isolated)



Dimensions in mm/ inches



SPA08N80C3

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